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a lower housing made of a highly thermal conductive material;

a blade portion;

a second magnet portion having a plurality of second magnets, wherein a permanent magnetic field is formed between said plurality of first magnets and said plurality of second magnets; and

2. The heat-dissipating module according to claim 1, wherein said heat-generating device is a CPU (central processing unit) in operation.

4. The heat-dissipating module according to claim 1, wherein a plurality of fins are disposed on a second surface of said lower housing.

6. The heat-dissipating module according to claim 1, wherein said highly thermal conductive material is one selected from a group consisting of aluminum, copper, aluminum alloy and copper alloy.

7. The heat-dissipating module according to claim 1, wherein said blade portion comprises a frame and a plurality of blades, said frame being ring-shaped and said plurality of blades being coupled to a bottom surface of said frame.

8. The heat-dissipating module according to claim 7, wherein an inner edge of said frame has a protrusion coupled to said second magnet portion.

9. The heat-dissipating module according to claim 1, wherein said second magnet portion comprises a support, a shaft and at least one rib, a free end of said shaft being inserted into a sleeve of said lower housing, and said at least one rib being interconnected with the other end of said shaft and said support.

10. The heat-dissipating module according to claim 9, wherein the number of said at least one rib is three.

11. The heat-dissipating module according to claim 10, said at least one rib is sheet-shaped and symmetrical about said shaft.

12. The heat-dissipating module according to claim 1, wherein each of said plurality of winding coils is a conducting line patterned on the circuit board for a plurality of turns.

13. A heat-dissipating module for removing heat generated from a heat-generating device, comprising:

a lower housing made of a highly thermal conductive material, and having a first surface in contact with said heat-generating device and a plurality of fins extending from a second surface thereof;

an upper housing having an opening in the center thereof, wherein when said upper housing and said lower housing are jointed together, an outlet is defined;

a blade portion;

a first magnet portion including a plurality of first magnets;

a second magnet portion having a plurality of second magnets, wherein a

permanent magnetic field is formed between said plurality of first magnets and said plurality of second magnets; and

a circuit board between said first magnet portion and said second magnet portion and having a plurality of winding coils, wherein when a current is applied to said plurality of winding coils, said permanent magnetic field is repulsed to rotate said blade portion, and an ambient air flow is inhaled from said opening and exhaled via said outlet.

14. The heat-dissipating module according to claim 13, wherein said heat-generating device is a CPU (central processing unit) in operation.

15. The heat-dissipating module according to claim 13, wherein said fins are pin-shaped.

16. The heat-dissipating module according to claim 13, wherein said highly thermal conductive material is one selected from a group consisting of aluminum, copper, aluminum alloy and copper alloy.

17. The heat-dissipating module according to claim 13, wherein said blade portion comprises a frame and a plurality of blades, said frame being ring-shaped and said plurality of blades being coupled to a bottom surface of said frame.

18. The heat-dissipating module according to claim 17, wherein an inner edge of said frame has a protrusion coupled to said second magnet portion.

19. The heat-dissipating module according to claim 13, wherein said second magnet portion comprises a support, a shaft and at least one rib, a free end of said shaft being inserted into a sleeve of said lower housing, and said at least one rib being interconnected with the other end of said shaft and said support.

20. The heat-dissipating module according to claim 13, wherein each of said plurality of winding coils is a conducting line patterned on the circuit board for a plurality of turns.